

## Product / Process Change Notice

**Parts Affected:**

Chip process CPS041, Silicon Controlled Rectifiers.

**Part Numbers Affected:**

|       |        |
|-------|--------|
| CS92B | 2N5060 |
| CS92D | 2N5061 |
| CS92M | 2N5062 |
| CS92N | 2N5063 |
|       | 2N5064 |

**Extent of Change:**

The CPS041 wafer process has been discontinued and replaced with the CPS043 wafer process. There have been slight changes in die size that do not negatively impact electrical performance.

**Reason for Change:**

An alternate wafer foundry was approved for this process in order to enhance capacity and mitigate any future disruption to product supply.

**Effect of Change:**

This change does not affect the electrical characteristics of the product. Updated curves to be provided upon completion of qualification.

**Qualification:**

Standard evaluation and qualification testing is in-process.

**Effective Date of Change:**

Existing inventory will be shipped until depleted.

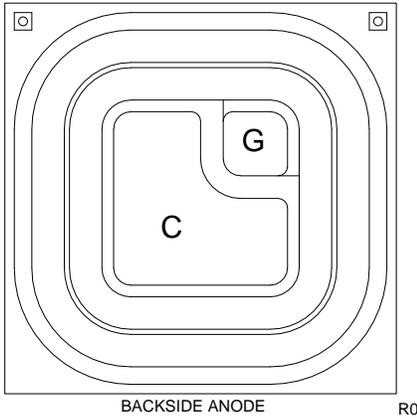
**Sample Availability:**

Please contact your salesperson or manufacturer's representative for samples.

**PCN #157**  
**Notification Date:**  
**January 12, 2017**

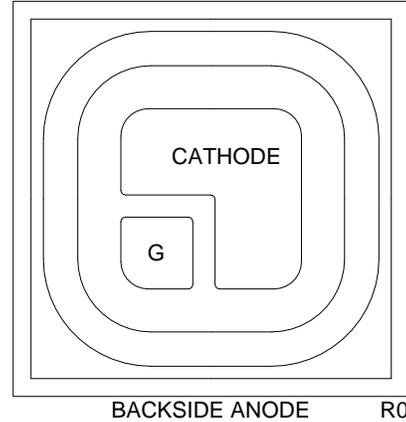
**Figures:**

**Figure 1: CPS041 Chip Geometry (Discontinued)**



|                          |   |
|--------------------------|---|
| Wafer Diameter:          | 4 inch  |
| Die Size:                | 41 x 41 mils                                  |
| Die Thickness:           | 8.7 mils                                      |
| Bond Pad Size (Cathode): | 18 x 8 mils                                   |
| Bond Pad Size (Gate):    | 7.1 x 7.1 mils                                |
| Topside Metal:           | Al (45,000Å)                                  |
| Backside Metal:          | Al/Mo/Ni/Ag<br>(20,000Å/5,000Å/5,000Å/2,000Å) |

**Figure 2: CPS043 Chip Geometry (Replacement)**



|                          |   |
|--------------------------|---|
| Wafer Diameter:          | 4 inch  |
| Die Size:                | 43.3 x 43.3 mils                              |
| Die Thickness:           | 8.3 mils                                      |
| Bond Pad Size (Cathode): | 19.7x 9.5 mils                                |
| Bond Pad Size (Gate):    | 7.9 x 7.9 mils                                |
| Topside Metal:           | Al (30,000Å)                                  |
| Backside Metal:          | Al/Mo/Ni/Ag<br>(20,000Å/5,000Å/5,000Å/2,000Å) |



145 Adams Avenue, Hauppauge, NY 11788 USA  
Tel: (631) 435-1110 • Fax: (631) 435-1824  
[www.centrialsemi.com](http://www.centrialsemi.com)  
<mailto:processchange@centrialsemi.com>  
<http://www.centrialsemi.com/processchange>

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As per JEDEC standard JESD46, Customer Notification of Product/Process Changes by Solid-State Suppliers, a lack of acknowledgement of a PCN within thirty (30) days constitutes acceptance of the change.

The undersigned acknowledges and accepts Central Semiconductor's Product/Process Change Notification (PCN).

|               |  |
|---------------|--|
| Company Name: |  |
| Address:      |  |
|               |  |
|               |  |
| Printed Name: |  |
| Title:        |  |
| Signature:    |  |
| Date:         |  |